

Title (en)
Method for improving substrate adhesion in fluoropolymer deposition processes

Title (de)
Verfahren zur Verbesserung der Adhäsion im Fluorpolymerbeschichtungsverfahren

Title (fr)
Procédé d'amélioration de l'adhésion dans un procédé de dépôt de polymère fluoré

Publication
EP 0664343 B1 20000503 (EN)

Application
EP 95300002 A 19950103

Priority
US 17697294 A 19940103

Abstract (en)
[origin: US5900288A] A method of cleaning a substrate, in particular, the front face of a thermal ink jet printing device, to improve subsequent thin film deposition in a single chamber plasma processing system containing fluorine-containing deposits, involves treating the substrate with a hydrogen plasma. A front face coating for a thermal ink jet device may be formed by a method involving (1) treating a substrate of the thermal ink jet device with a hydrogen plasma; (2) optionally coating the cleaned substrate with an amorphous carbon layer; and (3) coating the substrate or amorphous carbon layer with a fluoropolymer layer.

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IPC 8 full level
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CPC (source: EP US)
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Cited by
EP0816096A3; EP0906828A3; US5936009A; US5888594A; US5948166A; DE102009000821A1; DE102009000821B4; US6659596B1; WO2017040912A1; WO9702904A1

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